

Electronic Graphene Devices through Tip-Based Nanotechnology

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Abstract and Introduction:

In order to test the electromechanical properties of graphene for this project, it was necessary to build a device that would actuate a graphene film mounted on a clamped-clamped thin-film plate of silicon nitride (SiN), which was then mechanically actuated using a piezoelectric actuator (PZT). Our device was fabricated by coating Si with a 400 nm layer of low stress nitride; the backside of the nitride was patterned and etched so that the Si layer could be completely etched by potassium hydroxide (KOH) to form nitride membranes on the front of the device. A 150 nm bi-layer of gold/chromium (Au/Cr) electrodes was deposited onto the front of the device to form a four-point probe measurement system. Bond wires were attached to electrodes to interface the device to a DIP package. Graphene was transferred on top of the device, so that its electrical conductivity and piezoresistivity could be measured.

The piezoresistivity tensor elements of graphene could be extracted by putting the 4-point probes on each side of the membrane. The elements were tensor because the piezoresistivity might be different, in different directions, due to a graphene samples' lack of directional uniformity. Using an optical interferometer, the vibration profile of the graphene/Si_xN_y films, mode shapes and amplitude could be measured as well. With this knowledge, graphene could be applied to microelectromechanical systems (MEMS) for smaller and more sensitive devices.

Despite the increase in publications on graphene, there is still not much known about its electromechanical properties. By having a better understanding of the tensor elements of graphene it could be applied to various MEMS such as resonators, transistors, and cantilevers.

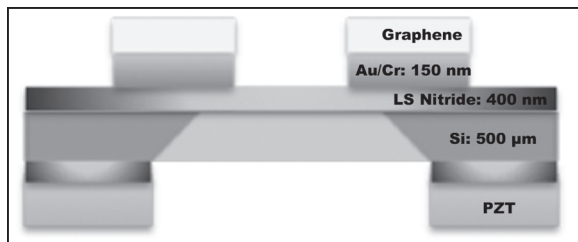


Figure 1: An illustration of the devices structure with example values for thicknesses.

Experimental Procedure:

Device fabrication consisted of nine steps.

1. About 400 nm of low stress nitride was deposited onto our Si wafers with low-pressure chemical vapor deposition (CVD).
2. Contact lithography was used to pattern the topside of the wafer in order to deposit a 150 nm bi-layer of Au/Cr electrodes.
3. Once the resist and excess metal were lifted off with 1165, the backside of the wafer was patterned and the nitride was etched to form windows in the bare Si.
4. Si was then completely etched with KOH to create nitride membranes ranging in size from 1500 μm to 50 μm squares. At this stage, the graphene was ready to be transferred onto our wafers that we diced into chips to make the process easier.
5. We used CVD-grown graphene that was deposited onto a copper (Cu) film and had poly(methyl methacrylate) (PMMA) spun onto it to make the graphene visible for transfer. A wet etch was used to remove the Cu from the graphene, and the graphene was then moved to de-ionized (DI) water to be repeatedly cleaned before it was transferred to our devices. The graphene placement was relatively easy as it was simply scooped out of the water onto a device and then left to air dry.
6. After the PMMA was removed with acetone, resist was spun onto the graphene and, using contact lithography, the graphene was patterned and then,
7. oxygen plasma etched so that only a 30 μm by 10 μm rectangle was left at the ends of our probes for our measurements.
8. A PZT was then attached to the backside of the devices followed by:
9. metal wire bonding leads, which were connected to the contact pads.

See Figure 1 for the complete layout of the design.

